



DIMENSIONS					
POSITION	A±0.20	B±0.20	C±0.25	D±0.25	E±0.25
36	6	7.65	9.15	25.00	27.00
64	20	21.65	23.15	39.00	41.00
98	37	38.65	40.15	56.00	58.00
164	70	71.65	73.15	89.00	91.00

NOTES 注释:

1. MATERIAL 材料:

1.1 HOUSING 外壳: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR: BLACK.

1.2 CONTACTS 触点: COPPER ALLOY.

1.3 HOLDDOWN 压具: COPPER ALLOY.

2. FINISH 饰面:

2.1 CONTACT 触点:

SELECTIVE GOLD PLATING ON CONTACT AREA.
100μ" MIN. MATTE TIN PLATING ON SOLDER TAILS,
50μ" MIN. NICKEL UNDERPLATING OVERALL.

2.2 HOLDDOWN 压具:

100μ" MIN. MATTE TIN PLATING WITH 50μ" MIN. NICKEL
UNDERPLATE OVERALL

X3113 W V S - XX - 9T V01

① ② ③ ④ ⑤ ⑥ ⑦

① Series Number

② Terminal form: W-Wafer

③ Welding Board Angle : V-Stright Angle 180°

④ Welding Way: S-SMT

⑤ No. of Pins: 36~164 Pin

⑥ Plastic material: PA9T/PA46 UL94V-0

⑦ Contact Plating: V01-Gold Flash 1u"
V15-Gold Flash 15u"
V30-Gold Flash 30u"

广东星坤科技股份有限公司

MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES
Δ					ANGLAR ±5°
Δ					L ≤ 4 ±0.2
Δ					4 < L ≤ 16 ±0.3
Δ					16 < L ≤ 63 ±0.4
Δ					L > 63 ±0.5



DSND	SCALE: N/A	MODEL TYPE:
DWN	VIEW:	PART NO.: X3113WVS-XX-9TV01
CHKD	UNIT: mm/in	DWG NO.: X-X3113WVS-XX-9TV01
APPD	SIZE: A4	WEIGHT SHEET REVISION
XKLB INDUSTRIAL PRECISION CO., LIMITED		1/1 A0